

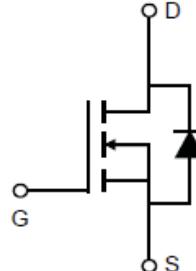
## N-Channel Super Trench Power MOSFET

### Description

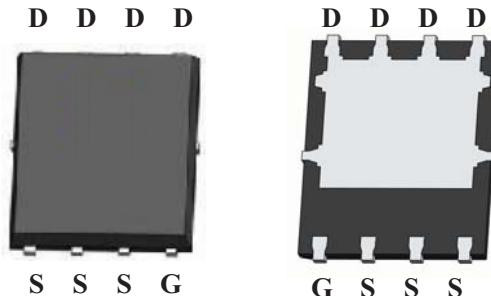
The RM150N40DF uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

### General Features

- $V_{DS} = 40V, I_D = 150A$
- $R_{DS(ON)} = 1.72m$  (typical) @  $V_{GS} = 10V$
- $R_{DS(ON)} = 2.3m$  (typical) @  $V_{GS} = 4.5V$
- Excellent gate charge  $\times R_{DS(on)}$  product(FOM)
- Very low on-resistance  $R_{DS(on)}$
- 150 °C operating temperature
- Pb-free lead plating
- 100% UIS tested



Schematic Diagram



Top View

Bottom View

**100% UIS TESTED!**  
**100%  $\Delta V_{ds}$  TESTED!**

### Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification
- Halogen-free

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
FN40	RM150N40DF	DFN5X6-8L	-	-	-

### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( <b>Silicon Limited</b> )	$I_D$	150	A
Drain Current-Continuous ( $T_c=100^\circ\text{C}$ )	$I_D (100^\circ\text{C})$	106	A
Pulsed Drain Current ( <b>Package Limited</b> )	$I_{DM}$	400	A
Maximum Power Dissipation	$P_D$	88	W
Derating factor		0.7	$\text{W}/^\circ\text{C}$
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	720	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

## Thermal Characteristic

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	R <sub>θJC</sub>	1.42	°C/W
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## Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	40		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.5	2.2	V
Drain-Source On-State Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =75A	-	1.72	2.1	m
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =75A	-	2.3	2.8	m
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =75A	-	80	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, F=1.0MHz	-	6000	7150	PF
Output Capacitance	C <sub>oss</sub>		-	1450	1700	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	100	145	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =20V, I <sub>D</sub> =75A V <sub>GS</sub> =10V, R <sub>G</sub> =1.6Ω	-	12.5	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	7.0	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	50	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	8.5	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =20V, I <sub>D</sub> =75A, V <sub>GS</sub> =10V	-	95	115	nC
Gate-Source Charge	Q <sub>gs</sub>		-	15		nC
Gate-Drain Charge	Q <sub>gd</sub>		-	11		nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =75A	-		1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	150	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = I <sub>S</sub> di/dt = 100A/μs <sup>(Note 3)</sup>	-		31	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-		110	nC

## Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition : T<sub>j</sub>=25°C, V<sub>DD</sub>=20V, V<sub>G</sub>=10V, L=0.5mH, R<sub>g</sub>=25Ω

## RATING AND CHARACTERISTICS CURVES (RM150N40DF)

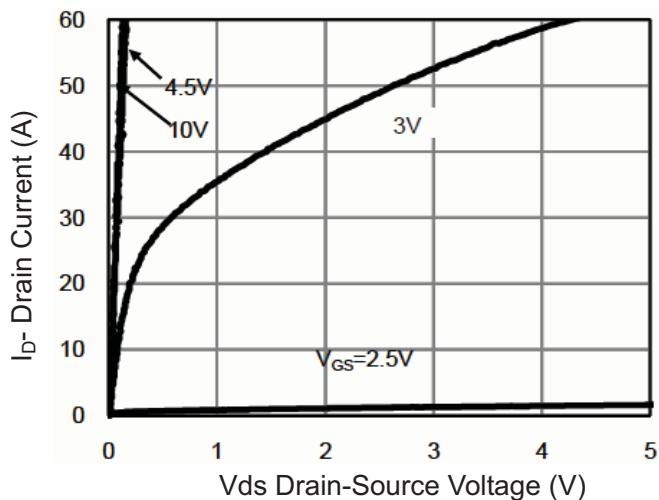


Figure 1 Output Characteristics

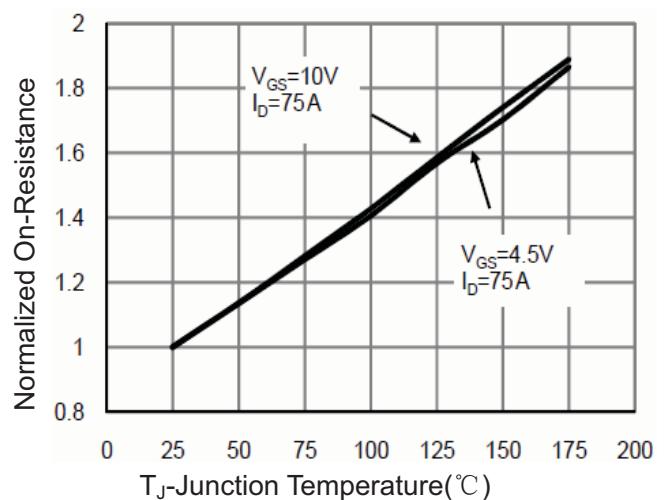


Figure 4 Rdson-JunctionTemperature

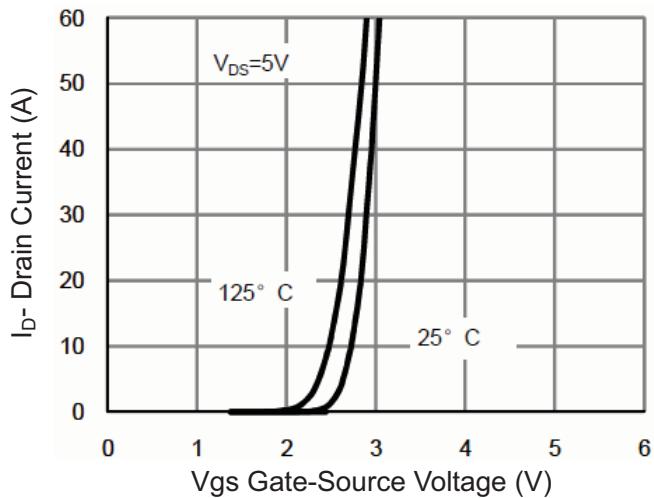


Figure 2 Transfer Characteristics

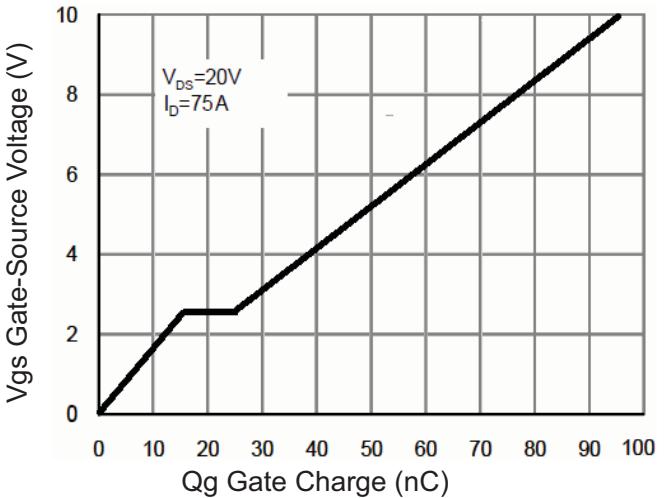


Figure 5 Gate Charge

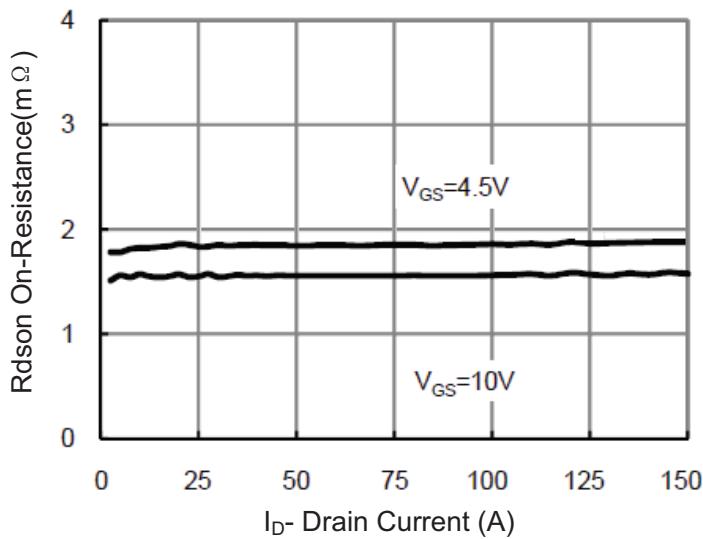


Figure 3 Rdson- Drain Current

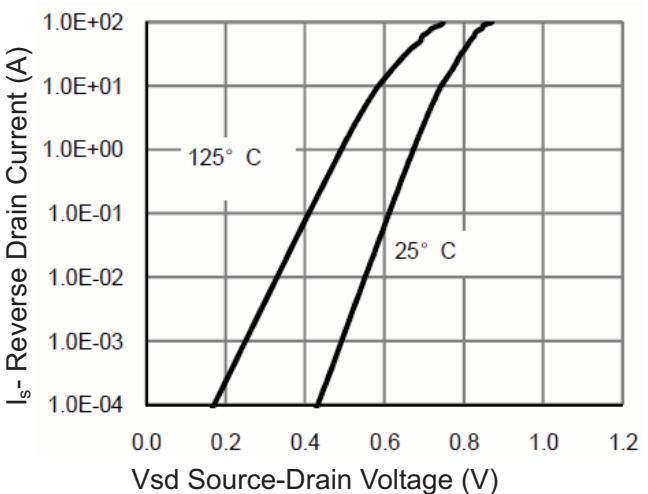
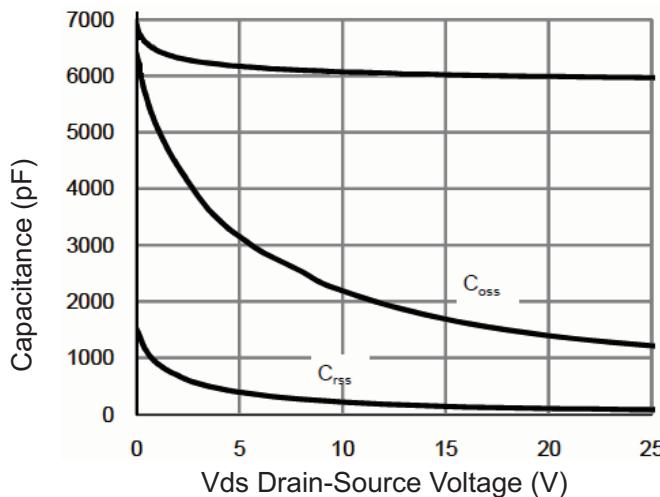
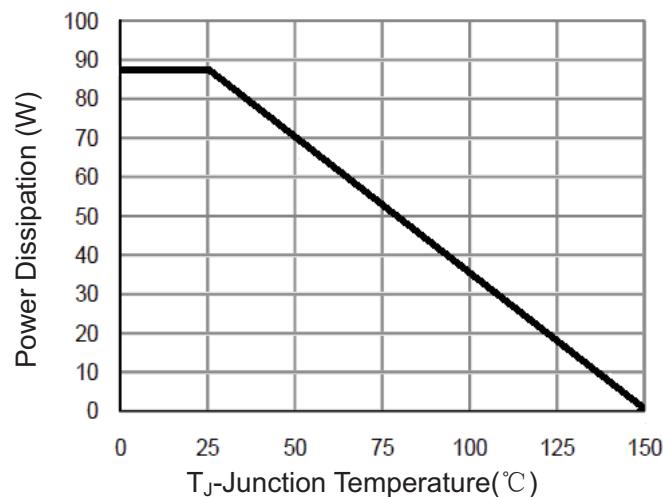


Figure 6 Source- Drain Diode Forward

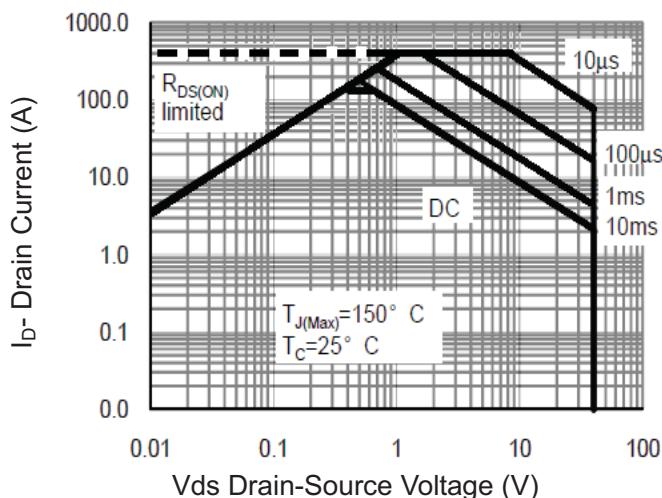
## RATING AND CHARACTERISTICS CURVES (RM150N40DF)



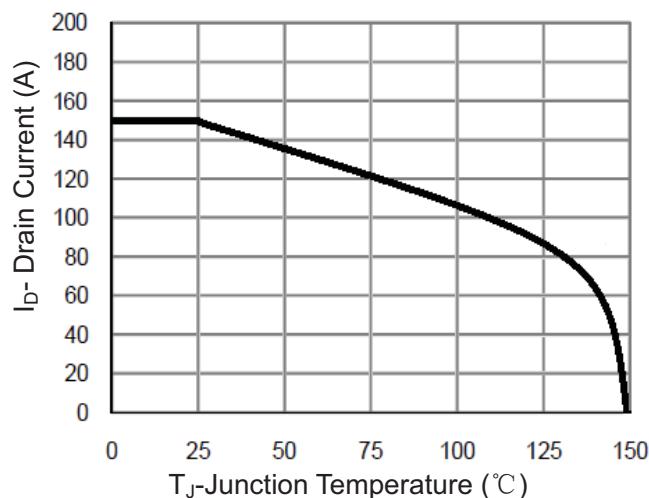
**Figure 7 Capacitance vs Vds**



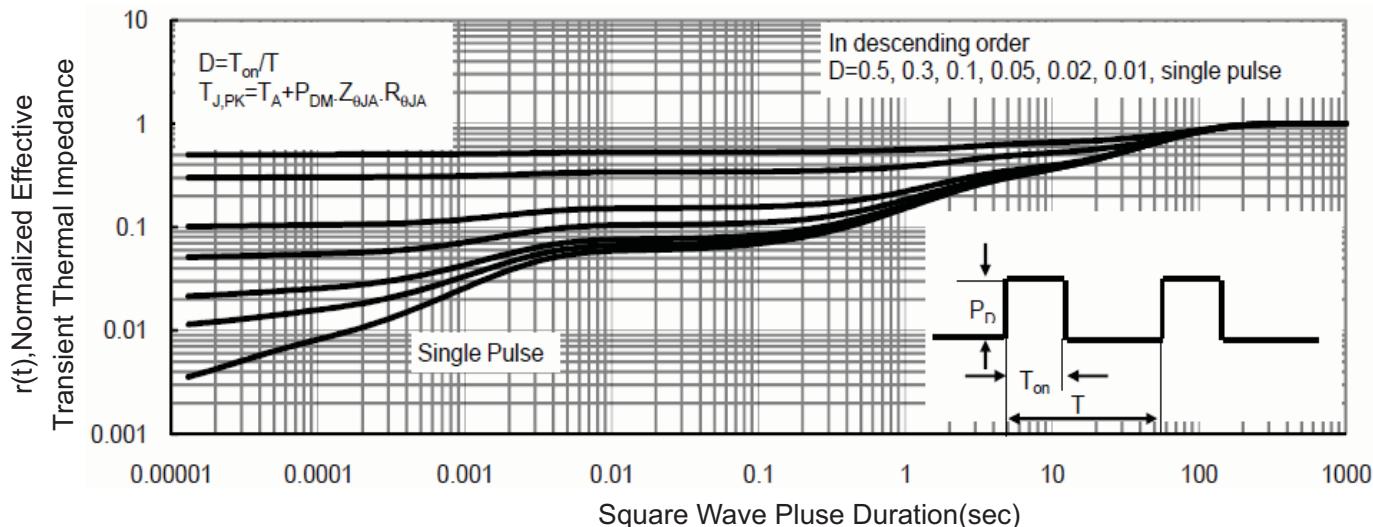
**Figure 9 Power De-rating**



**Figure 8 Safe Operation Area**

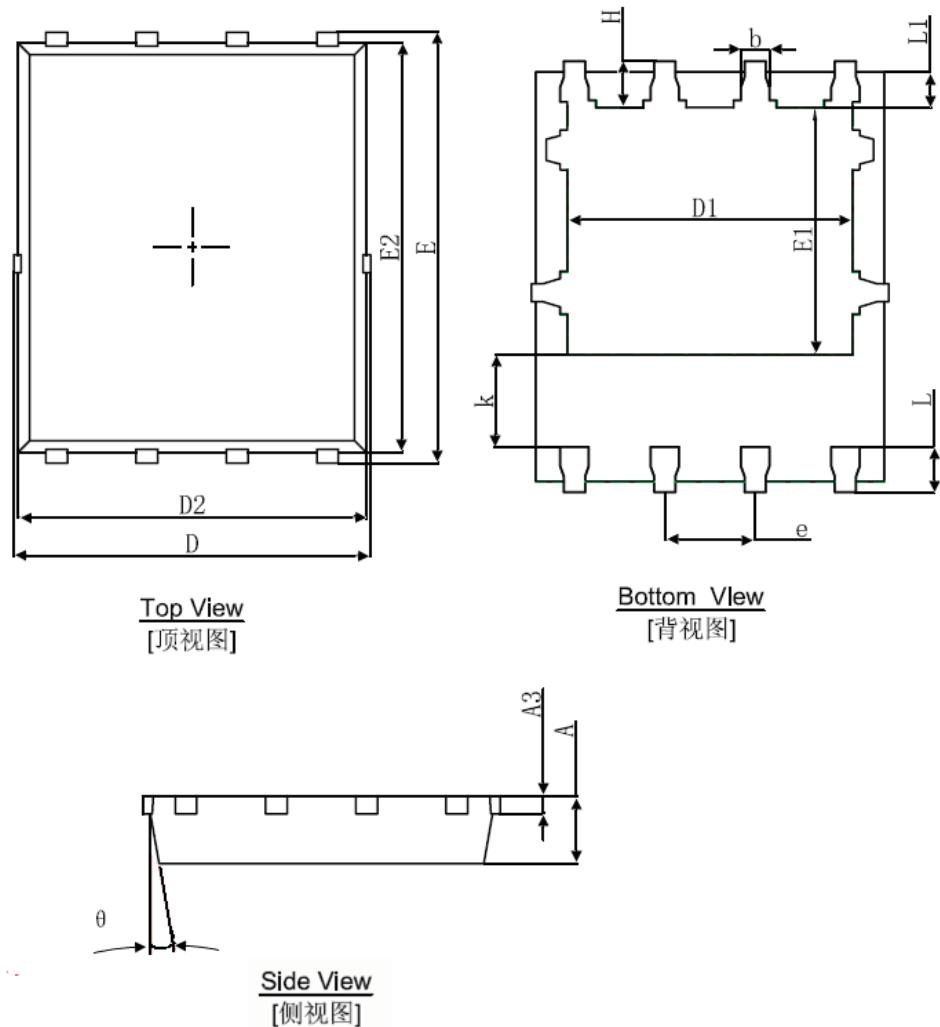


**Figure 10 Current De-rating**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## DFN5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°

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